



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2013-10-17
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Giuseppe Vitali Palma	Representative Title	AMS & IPD Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/internet/com/support/online_tech_support.jsp		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	CMDP*ML2PB62	A	SH1A	2013-10-17
Amount	UoM	Unit type	ST ECOPACK Grade	
370.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	6.5X6.1X2.3	3	gull wing	
Comment	Package: TO 252 DPAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	false
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList :REACH-20th June 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	CMDP*ML2PB62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	1.762	mg	supplier	die	Silicon (Si)	7440-21-3		1.723	mg	964726	5384
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.022	mg	12318	69
die (s)				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	560	3
die (s)				supplier	metallization	Nickel (Ni)	7440-02-0		0.012	mg	6719	38
die (s)				supplier	metallization	Silver (Ag)	7440-22-4		0.004	mg	2240	13
Leadframe	Copper & its alloys	180.947	mg	supplier	alloy	Copper (Cu)	7440-50-8		180.712	mg	998701	564725
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.181	mg	1000	566
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.054	mg	298	169
Soft solder	Other Organic Materials	1.76	mg	Jig Table R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	1.681	mg	955114	5253
Soft solder				supplier	solder	Silver (Ag)	7440-22-4		0.044	mg	25000	138
Soft solder				supplier	solder	Tin (Sn)	7440-31-5		0.035	mg	19886	109
Bonding wire	Other inorganic materials	0.138	mg	supplier	wire	Copper (Cu)	7440-50-8		0.138	mg	1000000	431
encapsulation	Other Organic Materials	184.348	mg	supplier	mold compound	Epoxy Resin	Proprietary		5.53	mg	29998	17281
encapsulation				supplier	mold compound	2,2'-(1,3,3',5,5'-tetramethyl-(1,1'-biphenyl)-4,4'	EC 413-900-7		7.374	mg	40000	23044
encapsulation				supplier	mold compound	phenol resin	Proprietary		9.217	mg	49998	28803
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		161.305	mg	875003	504078
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.922	mg	5001	2881
connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266